PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3102209

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Weng-Dah Ken	10/23/2014
Chao-Chun Lu	10/23/2014

RECEIVING PARTY DATA

Name:	Etron Technology, Inc.
Street Address:	No. 6, Technology Road 5
City:	Hsinchu
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14522567

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	ETRP0186USA
NAME OF SUBMITTER:	SHELLEY KUO
SIGNATURE:	/SHELLEY KUO/
DATE SIGNED:	11/11/2014

Total Attachments: 4
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PATENT

Docket No ETRP0186USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Weng-Dah Ken Nationality: TW

Name: Chao-Chun Lu Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Etron Technology, Inc.
Address: No. 6, Technology Road 5, Hsinchu 30078, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"SYSTEM-IN-PACKAGE MODULE WITH MEMORY"

Which is found in :

(a) ________ U.S. patent application executed on even date
(b) ________ U.S. patent application executed on ____________________
(c) + U.S. application serial no. 14/522,567
(d) _______ patent no. ____________________ issued ____________________
(e) ________ International application no. ______________

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this OCT 2 3 2014 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)	**Signature of INVENTOR**
Weng-Dah Ken	Weng-Dah Ken
Chao-Chun Lu	

PATENT

Docket No ETRP0186USA

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(Type name of inventor)	**Signature of INVENTOR**
Weng-Dah Ken	
Chao-Chun Lu	Chao Chun Lu